

Material Declaration Sheet

Vishav General Semiconductor - PDD

Date 28/Jul/16

Part / Product Family Details									
Vishay Part Number	RoHS Compliance Status	RoHS Compliance Date Code dd-mm-yyyy	Total product Weight (gm)	Resistance value	3rd Party Lab ICP Test Report Available	Manufacturing Location	Number of Exemptions Used		
P2SMAnnnA-E3 P4SMAnnA-(H) E3 SMA5Jxx(A)-(H) E3 SMAJxx(A)- (H) E3 SMAZ5919B-E3 to SMAZ5945B-E3 P4SMAnnCA-(H) E3 SMA5JxxC(A)-(H) E3 SMAJxC(A)-(H) E3	YES WITH EXEMPTION	01-12-2004	0.064	N/A	Yes	China	Two		

Technical Information: refer to http://www.vishay.com/how/leadfree/#summary

Terminal Plating / Grid	m	JESD-97 Pb-Free Material Code	J-STD-20D MSL	Reflow	Reflow	Reflow	Soldering Compatibility
Array Material	Terminal Base Alloy	Marking	Rating	Peak Process	Maximum	Max. Time at Peak	(SnPb/Pb-Free)
milay material		mor name	Rating	Body Temperature	number of cycles	Temperature (sec)	(5111 5) 1 5 1 1 0 0)

laterial Composition

Homogenous Material Name	Material Classification	Substance Name	CAS number	Weight of Substance (gm)	With respect to Homogenous Material		% with respect to Total Product Weight	RoHS Exemptions Used
					%	ppm	Total Hounce Weight	
Chip	Electronics (e.g. pc boards, displays)	Silicon and others (business secret)	-	0.00190	100.00	1000000	2. 97	Exemption No:7(c)-I
Lead Frame	Copper (e.g. copper amounts in cable harnesses)	Copper	7440-50-8	0. 02300	100.00	1000000	35. 94	
Solder 92.5	Other special metals	Lead	7439-92-1	0.00231	92. 50	925000	3. 61	Exemption No:7(a)
		Tin	7440-31-5	0.00013	5.00	50000	0. 20	
		Silver	7440-22-4	0.00006	2.50	25000	0.10	
Encapsulation	Other duromers	Quartz (SiO2)	14808-60-7	0. 02451	70.00	700000	38. 30	
		Epichlorohydrin, o-cresol, formalde polymer	29690-82-2	0.00558	16.00	160000	8. 73	
		Phenol-formaldehyde resin	9003-35-4	0.00419	12.00	120000	6. 54	
		Antimony oxide (Sb2-03)	1309-64-4	0.00035	1.00	10000	0.55	
•		Carbon-Black	1333-86-4	0.00009	0.25	2500	0.14	
		Additive & know-how	-	0.00026	0.75	7500	0.41	
Surface finish	Other special metals	Tin	7440-31-5	0.00160	100.00	1000000	2. 50	

EU-RoHS Directive— MCV of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated 2015/863/EU Diphenyl Ethers (PBDE) and MCV of 0.01% by mass cadmium, Bis(2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (DBP), Dibutyl phthalate (DBP) and Dijsobutyl phthalate (DBP)

This MDS vaild for List of PN's

Exemption Used 7(a) - Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

2nd Exemption Used 7(c)-I - Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound

Note :- (i) All information is based on data received from our vendors & subjected to change without prior notice.

(ii) Substance weight are derived from MSDS.



